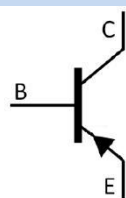


/ Descriptions

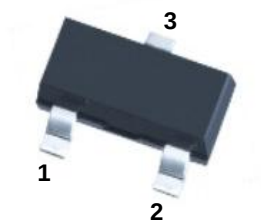
/ Features

/ Applications

/ Equivalent Circuit



/ Pinning



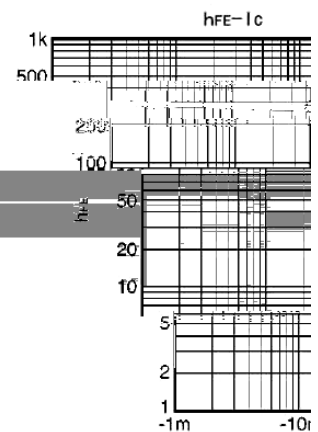
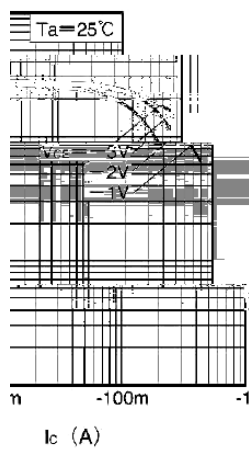
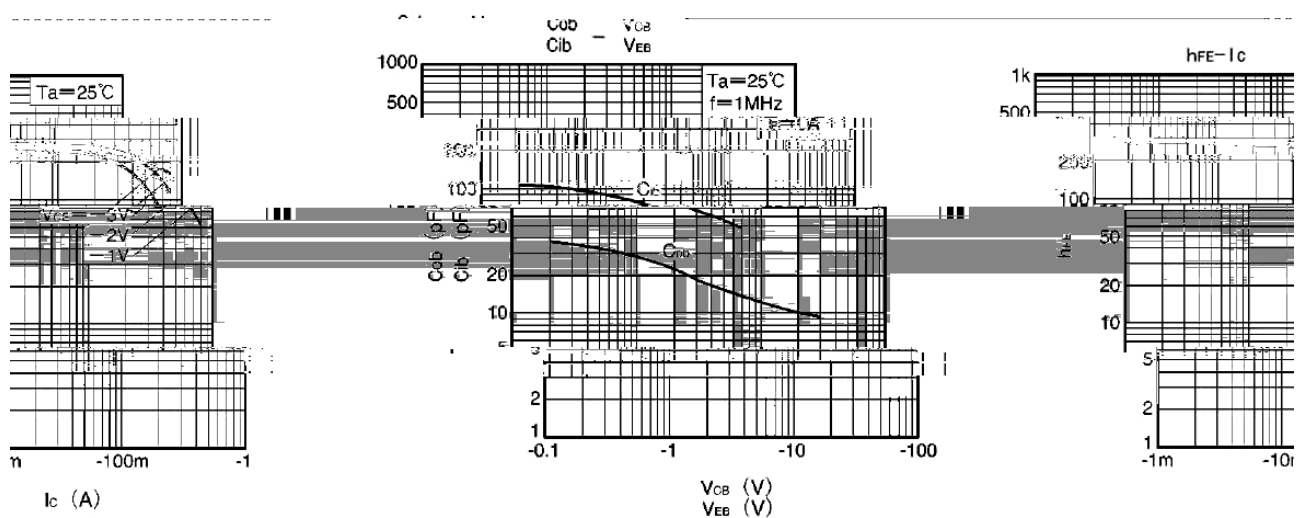
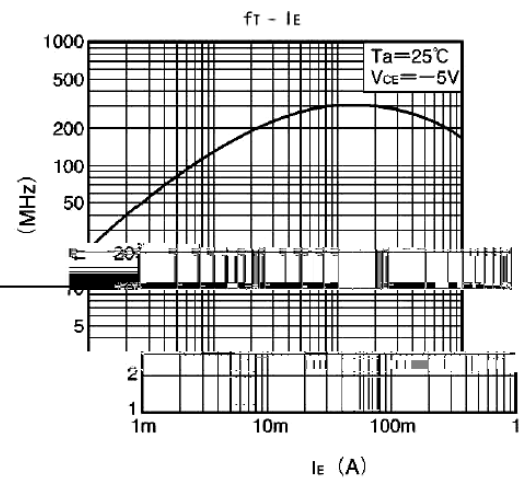
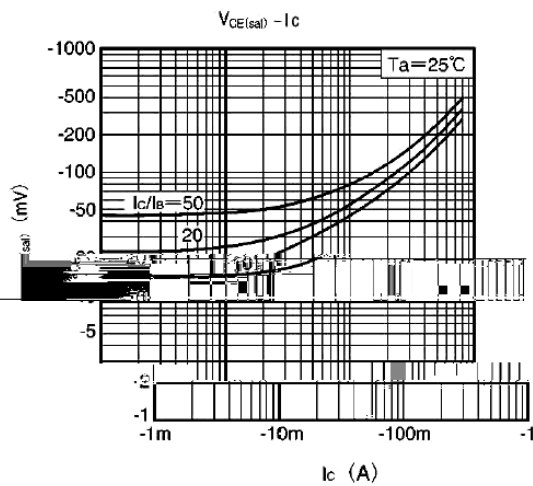
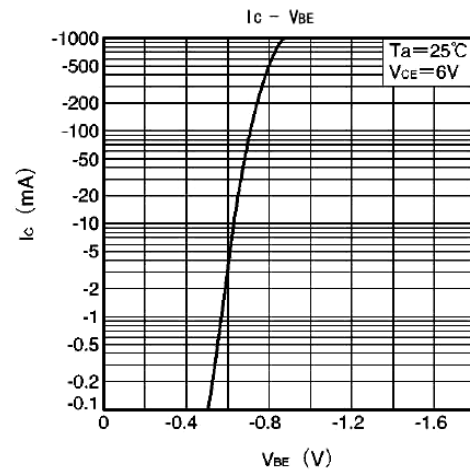
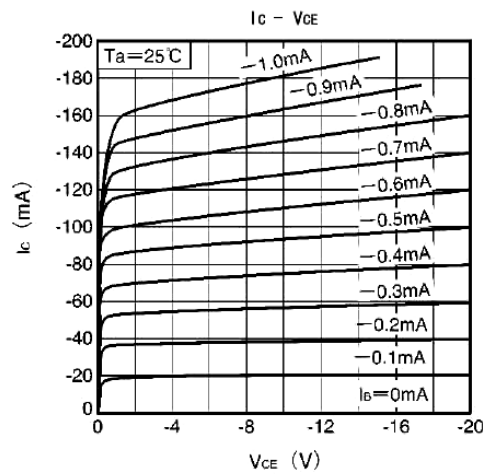
/ h_{FE} Classifications & Marking

	~	~

			℃
		~	℃

		μ				
		μ				
						μ
						μ

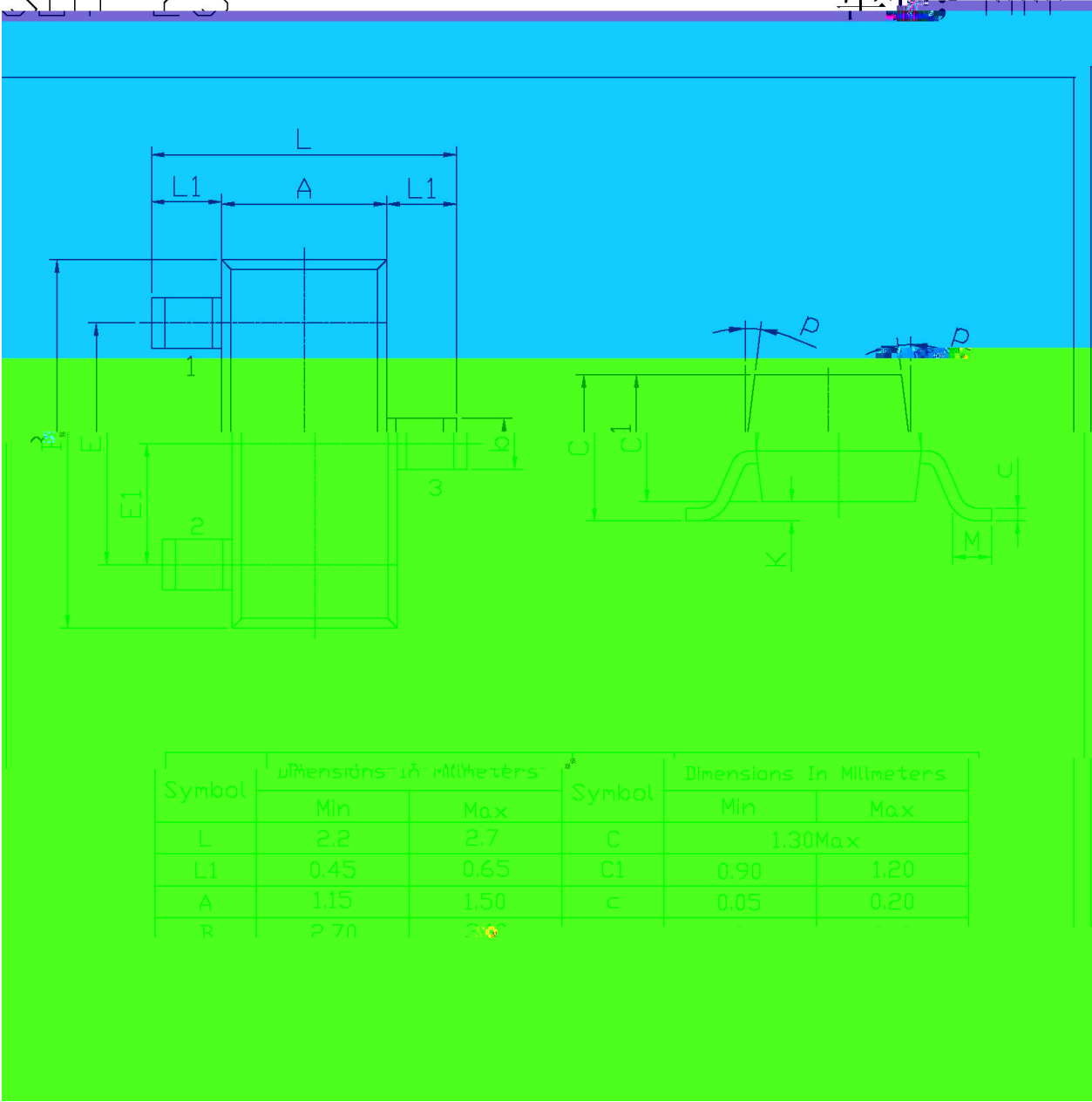
/ Electrical Characteristic Curve



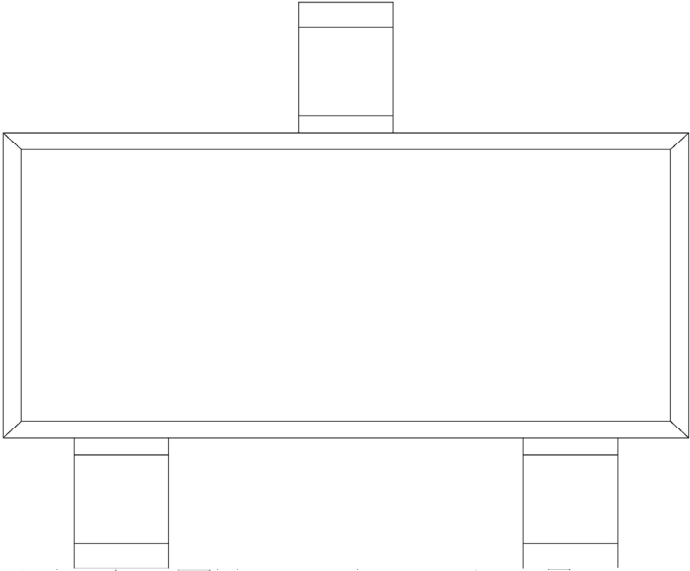
/ Package Dimensions

SOT-23

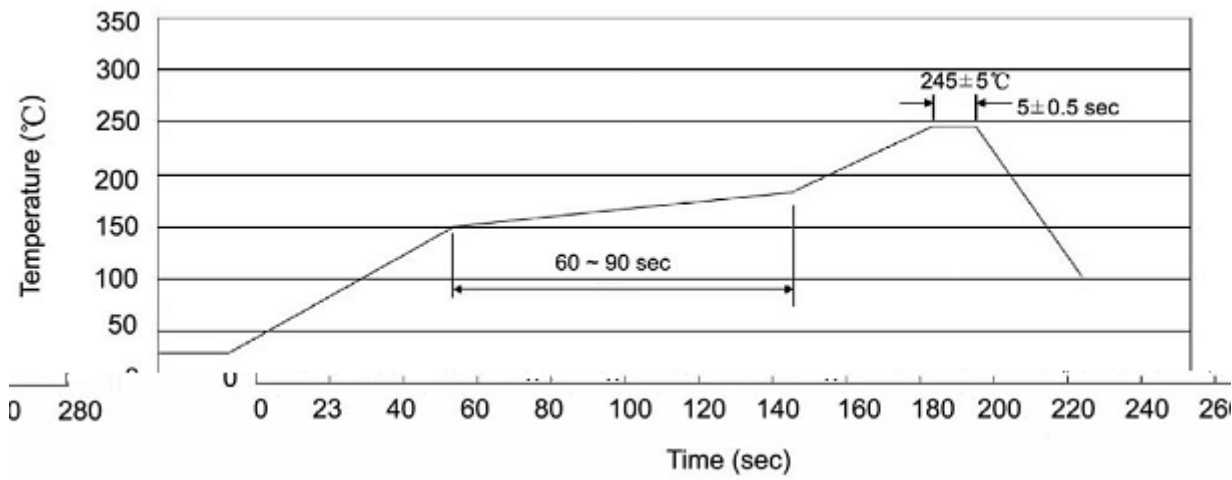
单位: mm



/ Marking Instructions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

℃

℃

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices